WHAT IS CLAIMED IS:

1. An electronic device comprising:

an element carrying substrate having an electronic element and a first electrode, said first electrode disposed on a surface of said element carrying substrate and having a prescribed area;

a wiring substrate arranged to face said element carrying substrate and having a second electrode disposed on a surface of said wiring substrate, said second electrode having a prescribed area and facing said first electrode; and

a coupler disposed between said first electrode and said second electrode to join said element carrying substrate and said wiring substrate, said coupler having a resin body and an electroconductive member, the surface of said coupler comprising a resin region and an electroconductive region to thereby electrically connect said first electrode and said second electrode.

2. An electronic device as claimed in claim 1, wherein the resin region occupies from 20 to 80% of the surface area of the coupler.

3. An electronic device as claimed in claim 1, wherein the electroconductive member is formed from a joining metal and the electroconductive region is formed by the joining metal locating on the surface of the coupler.

4. An electronic device as claimed in claim 1, wherein

the electroconductive member comprises metal powder with a high melting point and the electroconductive region is formed by the metal powder locating on the surface of the coupler, the metal powder having a joining metal film joined thereto.

5. An electronic device as claimed in claim 1, wherein the electroconductive member comprises a metal strip layer having a joining metal film joined thereto, the metal strip layer encircling the resin body to thereby form the electroconductive region.

6. An electronic device as claimed in claim 5, wherein the metal strip layer has an opening disposed substantially at a center of the element carrying substrate and the wiring substrate.

7. An electronic device as claimed in claim 1, wherein the resin body is formed from a thermosetting resin.

8. An electronic device as claimed in claim 1, wherein the resin body is formed from a thermoplastic resin.

9. A coupler with a spherical shape comprising a blend of a joining metal and a resin, wherein the surface of said coupler comprises an electroconductive region formed by the joining metal an a resin region formed by the resin.

10. A coupler with a spherical shape comprising a resin body and metal powder with a high melting point, the surface of the coupler comprising an electroconductive region and a resin region, wherein the metal powder locating on the surface

of the coupler has a joining metal film joined thereto to form the electroconductive region.

11. A coupler with a spherical shape comprising a resin ball and a metal strip layer, the metal strip layer encircling the resin body and having an opening, wherein the metal strip layer has a joining metal film joined thereto.